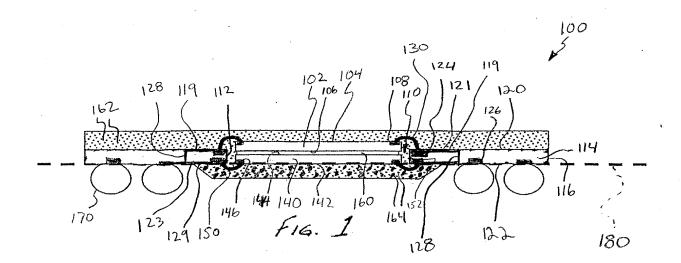
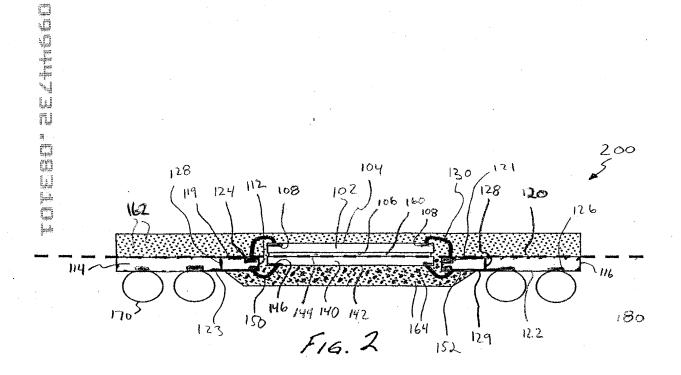
Title: Thin Semiconductor Package Includes Stacked Dies

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Inventors: Lee John Smith and David Albert Zoba Stacked Dies

Title: Thin Semiconductor Package Include

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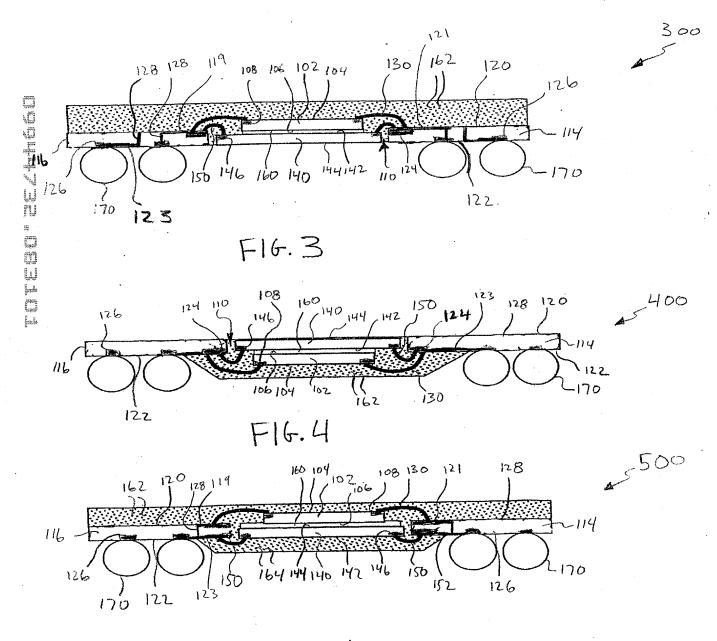
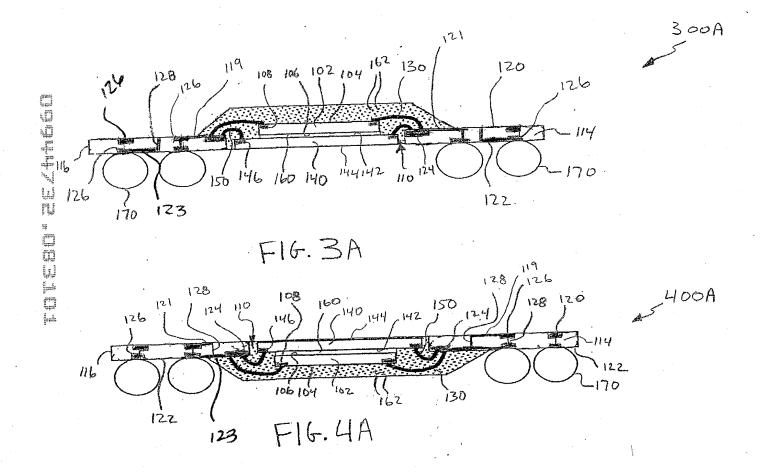


FIG. 5

Title: Thin Semiconductor Package Including Stacked Dies

Atty. Docket No.: M-11443 US

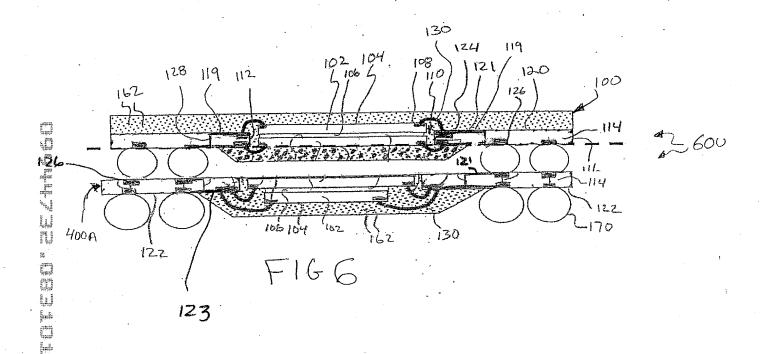
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Title: Thin Semiconductor Package Including Stacked Dies

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Title: Thin Semiconductor Package Include Stacked Dies

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Title: Thin Semiconductor Package Including tacked Dies

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